

In the Claims

1. (previously amended) A medical instrument comprising:
 - an instrument body having at least one outer surface,
 - a recess which is provided in said instrument body and which comprises a collar forming an undercut in at least one partial region of the recess, said collar having an inside diameter that is smaller than a length and a width of said recess,
 - a wireless readable data carrier embedded in said recess, said data carrier having outer dimensions which are smaller than said inside diameter, and
 - an embedding medium arranged between said data carrier and said recess and forming a body by means of which said data carrier is non-removeably held in said undercut.
2. (canceled)
3. (canceled)
4. (previously amended) The medical instrument of claim 1, wherein said embedding medium has a first elasticity modulus and said instrument body has a second elasticity modulus, and wherein said first elasticity modulus is larger than said second elasticity modulus.
5. (previously amended) The medical instrument of claim 1, wherein said embedding medium has a first elasticity modulus and said instrument body has a second elasticity modulus, and wherein said first elasticity modulus is smaller than said second elasticity modulus.
6. (canceled)

7. (withdrawn)
8. (previously amended) The medical instrument of claim 1, wherein said embedding medium has a first heat conductivity, wherein said instrument body has a second heat conductivity, and wherein said first heat conductivity is smaller than said second heat conductivity.
9. (previously amended) The medical instrument of claim 1, further comprising at least one spacer arranged between said data carrier and said recess.
10. (withdrawn)
11. (original) The medical instrument of claim 1, wherein said recess comprises an opening which forms a window in said outer surface of said instrument body.
12. (original) The medical instrument of claim 1, wherein said recess is made visually recognizable in the region of said outer surface.
13. (original) The medical instrument of claim 1, wherein said data carrier is surrounded by a glass casing.
14. (original) The medical instrument of claim 1, wherein said data carrier includes a transponder having an antenna.
15. (withdrawn)
16. (canceled)

17. (new) A medical instrument comprising:

an instrument body having an outer surface,

a recess provided in said instrument body including a collar having a length L_K and a width B_K forming an undercut in at least one partial region of the recess, said recess having a length L_H and a width B_H , where L_H is greater than L_K and B_H is greater than B_K ;

a wireless readable data carrier embedded in said recess, said data carrier having a length L_T , where L_T is less than L_K ; and

an embedding medium arranged between said data carrier and said recess and forming a body by means of which said data carrier is non-removable held in said undercut.

18. (new) The medical instrument according to claim 17 where said recess includes an opening at a top of said recess having a length L_O and a width B_O , where L_O is greater than L_K and B_O is greater than B_K .

19. (new) The medical instrument according to claim 18 where L_O is greater than L_H .

20. (new) A medical instrument comprising:

an instrument body having an outer surface,

a recess which is provided in said instrument body and which comprises a collar forming an undercut in at least one partial region of the recess, said collar having an inside diameter that is smaller than a length and a width of said recess,

a wireless readable data carrier embedded in said recess, said data carrier having outer dimensions which are smaller than said inside diameter, and

an embedding medium encapsulating and forming a body around said data carrier such that said data carrier is decoupled from said instrument body wherein any me-

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chanical or thermal load acting upon said instrument body is not directly transferred to said data carrier.

21. (new) The medical instrument according to claim 20 wherein said embedding medium is selected from the group consisting of epoxy resin, cement, ceramic or combinations thereof.